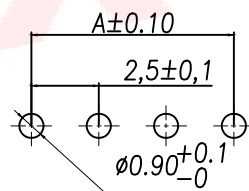
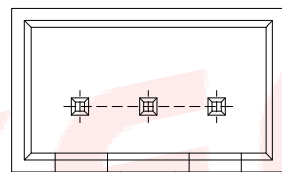
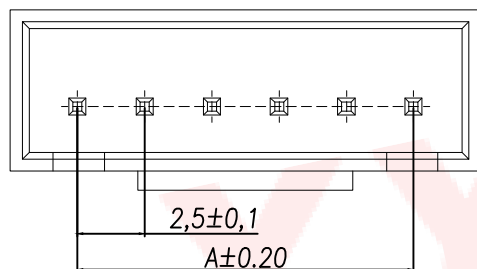
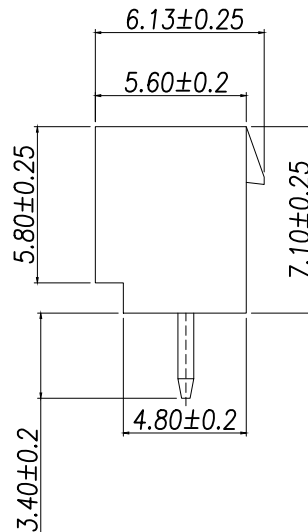
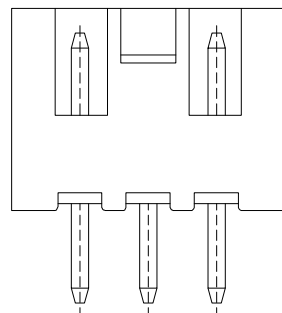
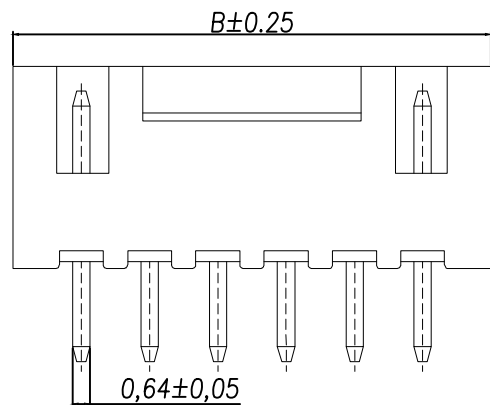


REV.	Q'TY	ECN. NO.	APR.	DATE



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度235 , 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B
XY-XHB2.5-2A-C	2	2.50	7.50
XY-XHB2.5-3A-C	3	5.00	10.00
XY-XHB2.5-4A-C	4	7.50	12.50
XY-XHB2.5-5A-C	5	10.00	15.00
XY-XHB2.5-6A-C	6	12.50	17.50
XY-XHB2.5-7A-C	7	15.00	20.00
XY-XHB2.5-8A-C	8	17.50	22.50
XY-XHB2.5-9A-C	9	20.00	25.00
XY-XHB2.5-10A-C	10	22.50	27.50
XY-XHB2.5-11A-C	11	25.00	30.00
XY-XHB2.5-12A-C	12	27.50	32.50
XY-XHB2.5-13A-C	13	30.00	35.00
XY-XHB2.5-14A-C	14	32.50	37.50
XY-XHB2.5-15A-C	15	35.00	40.00
XY-XHB2.5-16A-C	16	37.50	42.50
XY-XHB2.5-17A-C	17	40.00	45.00
XY-XHB2.5-18A-C	18	42.50	47.50
XY-XHB2.5-19A-C	19	45.00	50.00
XY-XHB2.5-20A-C	20	47.50	52.50

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyecomm Electronics Co.,Ltd			
TOLERANCE UNLESS OTHERWISE SPECIFIED		TITLE: WAFER XHB2.5MM 带扣 直针			
.X \pm 0.35	X.* \pm 5°	APR.	Alex	DWG NO. XY-XHB2.5-NA-C	
.XX \pm 0.25	.X* \pm 3°	CHK.	Jack	PROJ. CUSTOMER DRAWING	
.XXX \pm 0.15	.XX* \pm 1°	DRA.	Can	SIZE A4	SCALE 1:1
				SHEET 1/1	REV. A